(57) Abstract

A SAW element (13) is formed of a piezoelectric substrate (14), on which are provided IDT electrodes (15), connection electrodes (16), underlying metal layers (17), and acoustic materials (18) placed on the underlying metal layers (17) and having surfaces parallel to the main surface of the piezoelectric substrate (14). The SAW element is mounted in a package (10), which is provided with external terminals (11) connected with the connection electrodes (16), and the package is hermetically sealed with a lid (20) to form a SAW device. When such a SAW element (13) is mounted faceup in a package (10) using a vacuum chuck (30), its piezoelectric substrate (14) can be protected against damage. When a SAW element (13) provided with bumps (23) on its connection electrodes (16) is mounted facedown in a package (10), the failure of electrical connections can be prevented.